



IMPORTANT NOTICE

10 December 2015

1. Global joint venture starts operations as WeEn Semiconductors

Dear customer,

As from November 9th, 2015 NXP Semiconductors N.V. and Beijing JianGuang Asset Management Co. Ltd established Bipolar Power joint venture (JV), **WeEn Semiconductors**, which will be used in future Bipolar Power documents together with new contact details.

In this document where the previous NXP references remain, please use the new links as shown below.

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If you have any questions related to this document, please contact our nearest sales office via e-mail or phone (details via salesaddresses@ween-semi.com).

Thank you for your cooperation and understanding,

WeEn Semiconductors



DATA SHEET

BYT79 series
Rectifier diodes
ultrafast

Product specification

September 1998



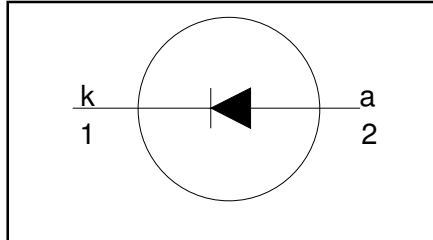
**Rectifier diodes
ultrafast**

BYT79 series

FEATURES

- Low forward volt drop
- Fast switching
- Soft recovery characteristic
- High thermal cycling performance
- Low thermal resistance

SYMBOL



QUICK REFERENCE DATA

$V_R = 300\text{ V} / 400\text{ V} / 500\text{ V}$
$V_F \leq 1.05\text{ V}$
$I_{F(AV)} = 14\text{ A}$
$t_{tr} \leq 60\text{ ns}$

GENERAL DESCRIPTION

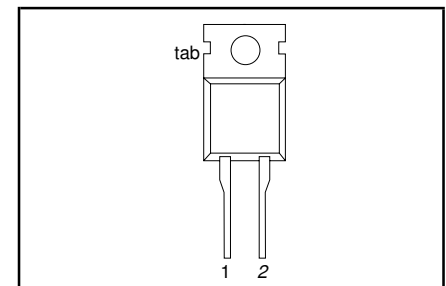
Ultra-fast, epitaxial rectifier diodes intended for use as output rectifiers in high frequency switched mode power supplies.

The BYT79 series is supplied in the conventional leaded SOD59 (TO220AC) package.

PINNING

PIN	DESCRIPTION
1	cathode
2	anode
tab	cathode

SOD59 (TO220AC)



LIMITING VALUES

Limiting values in accordance with the Absolute Maximum System (IEC 134).

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.			UNIT
				BYT79	-300	-400	
V_{RRM}	Peak repetitive reverse voltage	$T_{mb} \leq 147^\circ\text{C}$ square wave; $\delta = 0.5$; $T_{mb} \leq 117^\circ\text{C}$ $t = 10\text{ ms}$ $t = 8.3\text{ ms}$ sinusoidal; with reappplied $V_{RRM(max)}$	-	300	400	500	V
V_R	Continuous reverse voltage		-	300	400	500	V
$I_{F(AV)}$	Average forward current ¹		-	14			A
I_{FSM}	Non-repetitive peak forward current.		-	130			A
				143			A
T_{stg}	Storage temperature		-40	150			$^\circ\text{C}$
T_j	Operating junction temperature		-	150			$^\circ\text{C}$

THERMAL RESISTANCES

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
$R_{th\ j-mb}$	Thermal resistance junction to mounting base		-	-	2.0	K/W
$R_{th\ j-a}$	Thermal resistance junction to ambient	in free air.	-	60	-	K/W

¹ Neglecting switching and reverse current losses

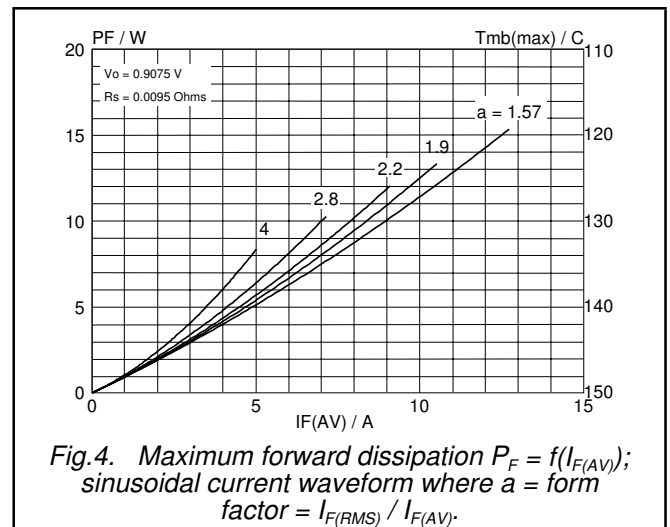
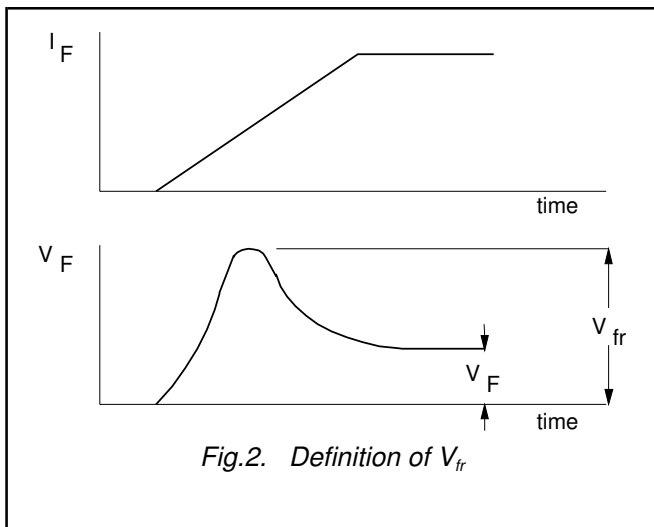
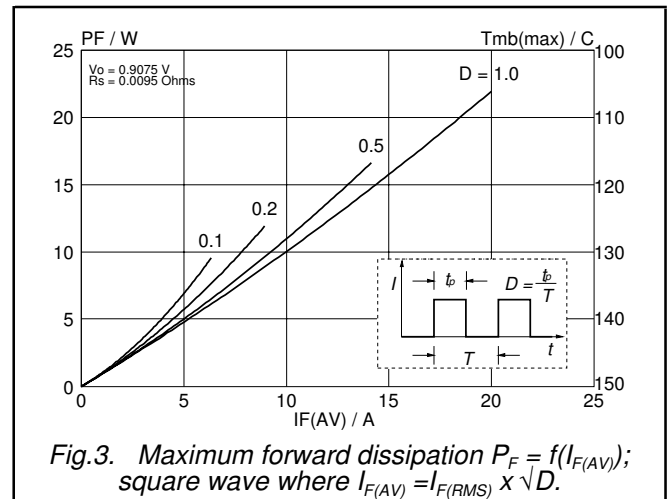
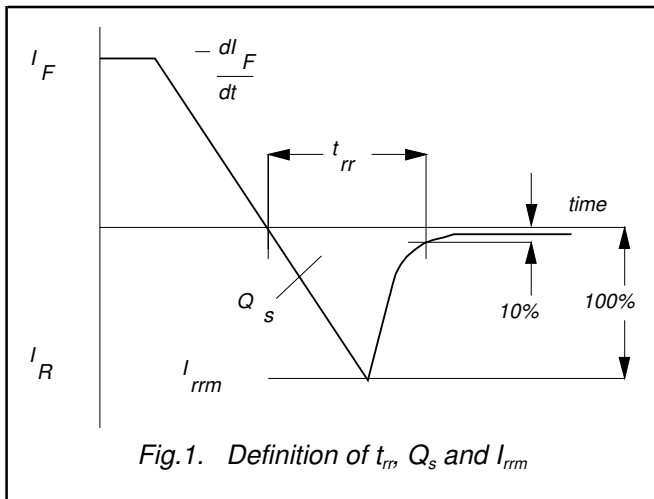
Rectifier diodes
ultrafast

BYT79 series

ELECTRICAL CHARACTERISTICS

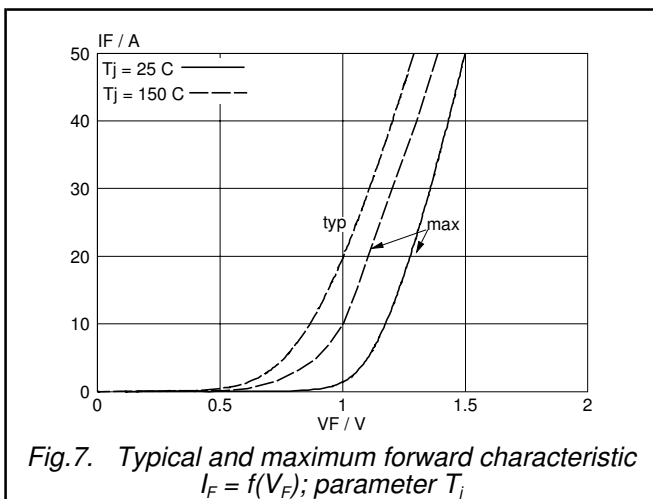
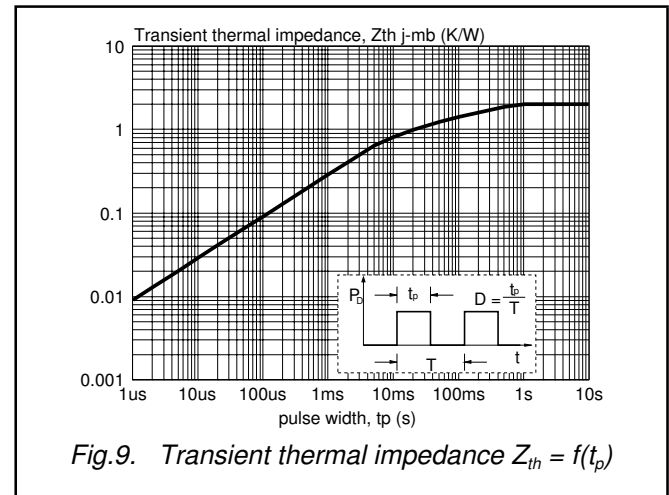
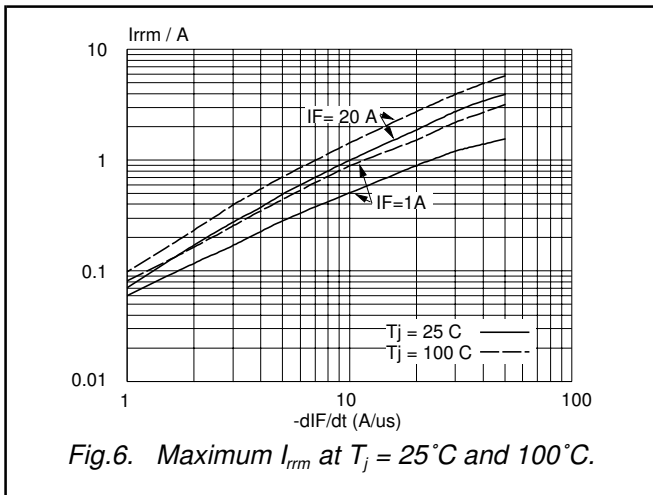
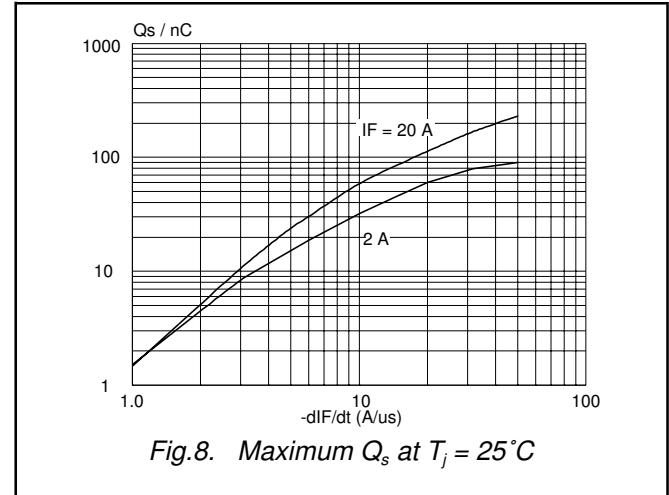
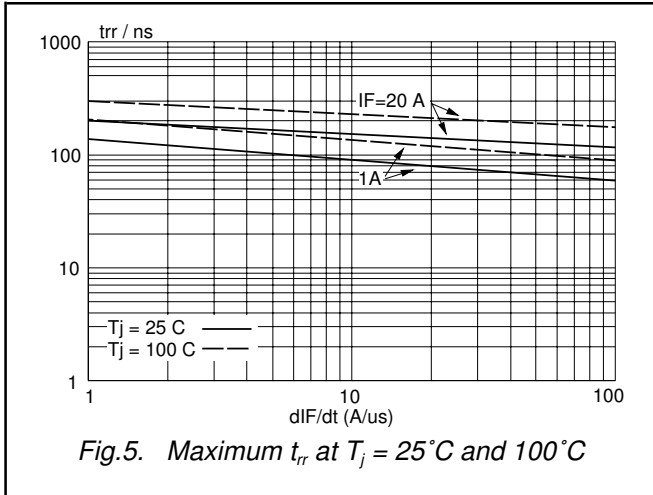
$T_j = 25\text{ }^\circ\text{C}$ unless otherwise stated

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
V_F	Forward voltage	$I_F = 15\text{ A}; T_j = 150\text{ }^\circ\text{C}$	-	0.90	1.05	V
		$I_F = 30\text{ A}$	-	1.17	1.38	V
I_R	Reverse current	$V_R = V_{RRM}$	-	5.0	50	μA
		$V_R = V_{RRM}; T_j = 100\text{ }^\circ\text{C}$	-	0.2	0.8	mA
Q_s	Reverse recovery charge	$I_F = 2\text{ A to } V_R \geq 30\text{ V};$ $di_F/dt = 20\text{ A}/\mu\text{s}$	-	50	60	nC
t_{rr}	Reverse recovery time	$I_F = 1\text{ A to } V_R \geq 30\text{ V};$ $di_F/dt = 100\text{ A}/\mu\text{s}$	-	50	60	ns
I_{rrm}	Peak reverse recovery current	$I_F = 10\text{ A to } V_R \geq 30\text{ V};$ $di_F/dt = 50\text{ A}/\mu\text{s}; T_j = 100\text{ }^\circ\text{C}$	-	4.0	5.2	A
V_{fr}	Forward recovery voltage	$I_F = 10\text{ A}; di_F/dt = 10\text{ A}/\mu\text{s}$	-	2.5	-	V



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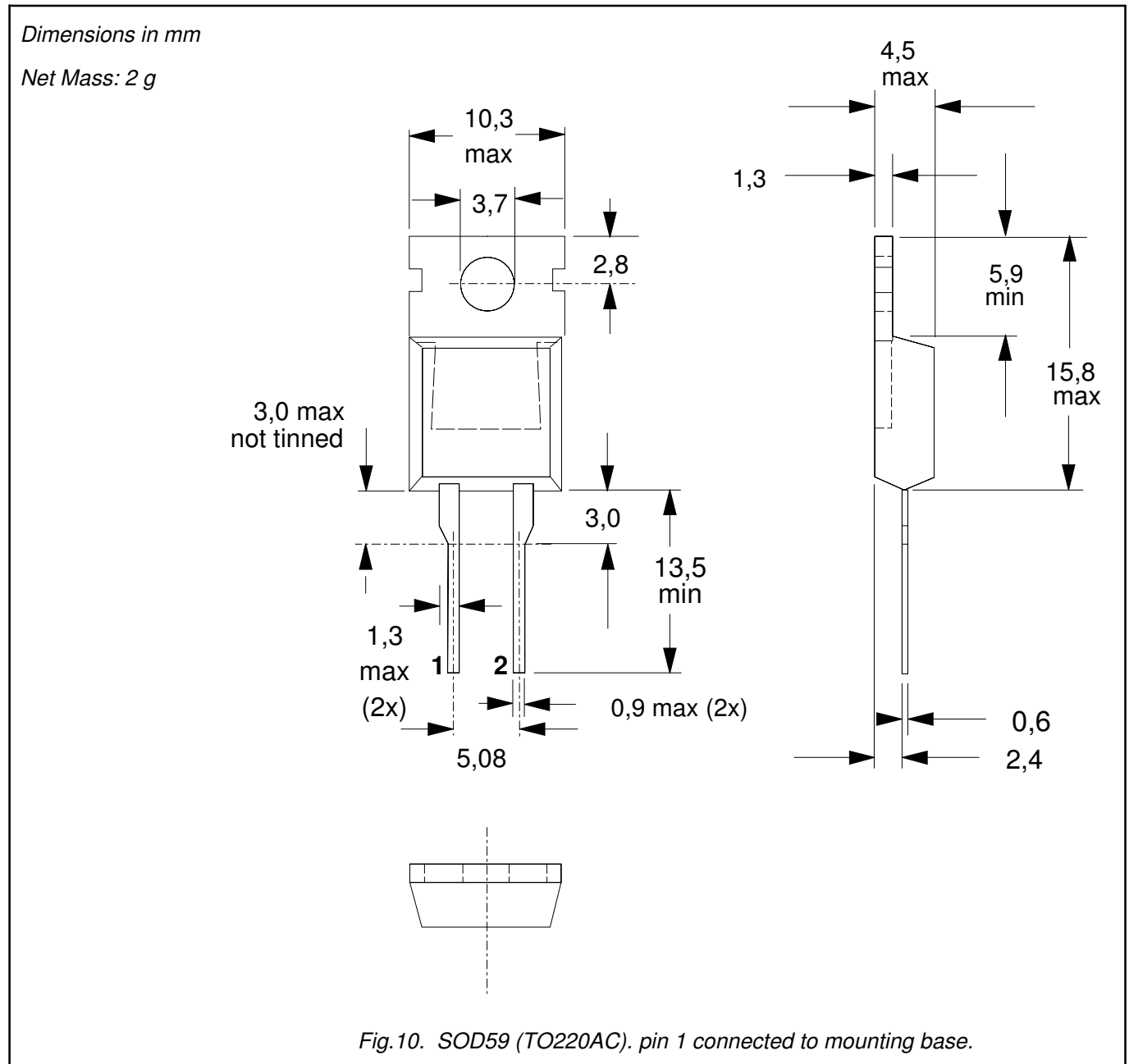
BYT79 series



Rectifier diodes
ultrafast

BYT79 series

MECHANICAL DATA



Notes

1. Refer to mounting instructions for TO220 envelopes.
2. Epoxy meets UL94 V0 at 1/8".

Legal information

DATA SHEET STATUS

DOCUMENT STATUS ⁽¹⁾	PRODUCT STATUS ⁽²⁾	DEFINITION
Objective data sheet	Development	This document contains data from the objective specification for product development.
Preliminary data sheet	Qualification	This document contains data from the preliminary specification.
Product data sheet	Production	This document contains the product specification.

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Customer notification

This data sheet was changed to reflect the new company name NXP Semiconductors, including new legal definitions and disclaimers. No changes were made to the content, except for the legal definitions and disclaimers.

Contact information

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